



Intelligent Sensing for Better and Smarter Living – MEMS & Imaging Sensors Summit Returns to Grenoble – June 7, 2022



GRENOBLE, France – June 7, 2022 – With MEMS and imaging sensor innovations driving an explosion in medical, mobility, communications and other Smart applications, the stage is set for the return of [SEMI MEMS & Imaging Sensors Summit](#), 6-7 September, 2022, to the World Trade Center (WTC) in Grenoble, France. More than 400 industry experts will gather for insights into the latest technology developments and trends across the MEMS and sensors supply chain. [Registration](#) is open.

Hosted by SEMI Europe and the [MEMS & Sensors Industry Group](#), a SEMI Technology Community, and Themed *Intelligent Sensing for Better and Smarter Living*, the summit will open with insightful executive keynotes and feature sessions on the following critical semiconductor industry topics.

Program Sessions

Session 1: A Diverse and Sustainable Workforce Enabling Next Generation Innovation

Industry leaders will explore how diversity drives innovation and ways companies and corporate leaders can create an inclusive environment where employees and innovation thrive.

Session 2: Market Brief

Industry trends, market drivers and supply chain dynamics will come into focus.

Session 3: Insights into Emerging Applications

Experts will share their vision for emerging sensor applications and discuss the latest developments in biosensors, MEMS, photonics and spectroscopic technologies.

Session 4: Intelligent Sensing

Discussions will highlight new sensor technologies that enable fast and reliable edge computing to pave the way for smarter applications in industries such as automotive and medical.

Session 5: Technology Showcase

This session will spotlight the latest MEMS and imaging sensor products and applications. Deep and traditional tech companies and startups as well as researchers developing new products will demonstrate cutting-edge solutions. Companies can [submit](#) their product demonstration abstracts by June 30.

Session 6.1: MEMS Advancements

Industry leaders will discuss new MEMS technology applications, devices and manufacturing trends. Application topics will include the integration of several sensors into System in Package (SiP), MEMS for medical sensing, and integrating data generation and data processing into the same system. Manufacturing topics will include advancements enabling 300mm wafer sizes, 3D integration and substrate diversification.

Session 6.2: Imaging Advancements

Industry leaders will share their visions for sensing processes, design and computing.

Session 7.1: Environmental MEMS Technology Focus

Future MEMS-enabled environmental technologies that drive advances in everything from preventative maintenance and quality control to environmental monitoring will come into sharp focus.

Session 7.2: The Latest on Short-wave Infrared (SWIR)

This session will explore the latest advancements in traditional SWIR imaging technology from **Lynred** and the promise of new quantum dot SWIR image sensors from **STMicroelectronics** and **Emberion**. It will also cover insights from **imec** on new consumer applications enabled by affordable sensors, and a low-cost solution for SWIR hyperspectral imaging introduced from **VTT**.

Session 8: Materials and Equipment Advancements

Experts will discuss how materials and equipment advances are enabling higher performance MEMS devices for new manufacturing techniques and equipment.

Session 9: Optics, Co-Packaged Optics (CPO) and Optical Chips Packaging for MEMS and Imaging Sensors

Rapid growth of cloud data presents new speed and bandwidth requirements. Industry leaders will explore the integration of optics and silicon through CPO to meet growing performance demands and reduce power consumption.

More MEMS & Imaging Sensors Summit Highlights

- Networking opportunities at the exhibition and a gala dinner for attendees of both MEMS and imaging sensor tracks to meet in-person.
- [Exhibition](#) showcasing leading companies driving the future of MEMS/imaging and sensors design and manufacturing including:
 - ASE Group
 - DELO Industrial Adhesives
 - Eurofins MASER B.V.
 - EV Group (EVG)
 - Evatec
 - Fraunhofer IPMS
 - KLA
 - Okmetic Oy
 - SAES Getters SpA
 - SCHOTT

- SET
- Siemens EDA (represented by EDA Solutions Limited)

Premier sponsors

- Platinum Sponsors: [ASE Group](#), [Infineon](#), [KLA](#), [SCHOTT](#)
- Gold Sponsors: [Evatec](#), [SUSS MicroTec Group](#)
- Silver Sponsor: [AEM](#)
- Event sponsors: [Caeleste](#), [EV Group \(EVG\)](#), [JSR Micro N.V.](#), [Okmetic](#)

For more information, please visit the [MEMS & Sensors Imaging Summit](#) website.

Stay in touch on Twitter @SEMIEurope: #SensorsSummit #MEMS #Imaging #SEMIEurope

About SEMI

SEMI® connects more than 2,500 member companies and 1.3 million professionals worldwide to advance the technology and business of electronics design and manufacturing. SEMI members are responsible for the innovations in materials, design, equipment, software, devices, and services that enable smarter, faster, more powerful, and more affordable electronic products. Electronic System Design Alliance (ESD Alliance), FlexTech, the Fab Owners Alliance (FOA), the MEMS & Sensors Industry Group (MSIG) and SOI Consortium are SEMI Strategic Technology Communities. Visit www.semi.org to learn more, contact one of our worldwide offices, and connect with SEMI on [LinkedIn](#) and [Twitter](#).

<https://www.3dincites.com/2022/06/intelligent-sensing-for-better-and-smarter-living-mems-imaging-sensors-summit-returns-to-grenoble/>